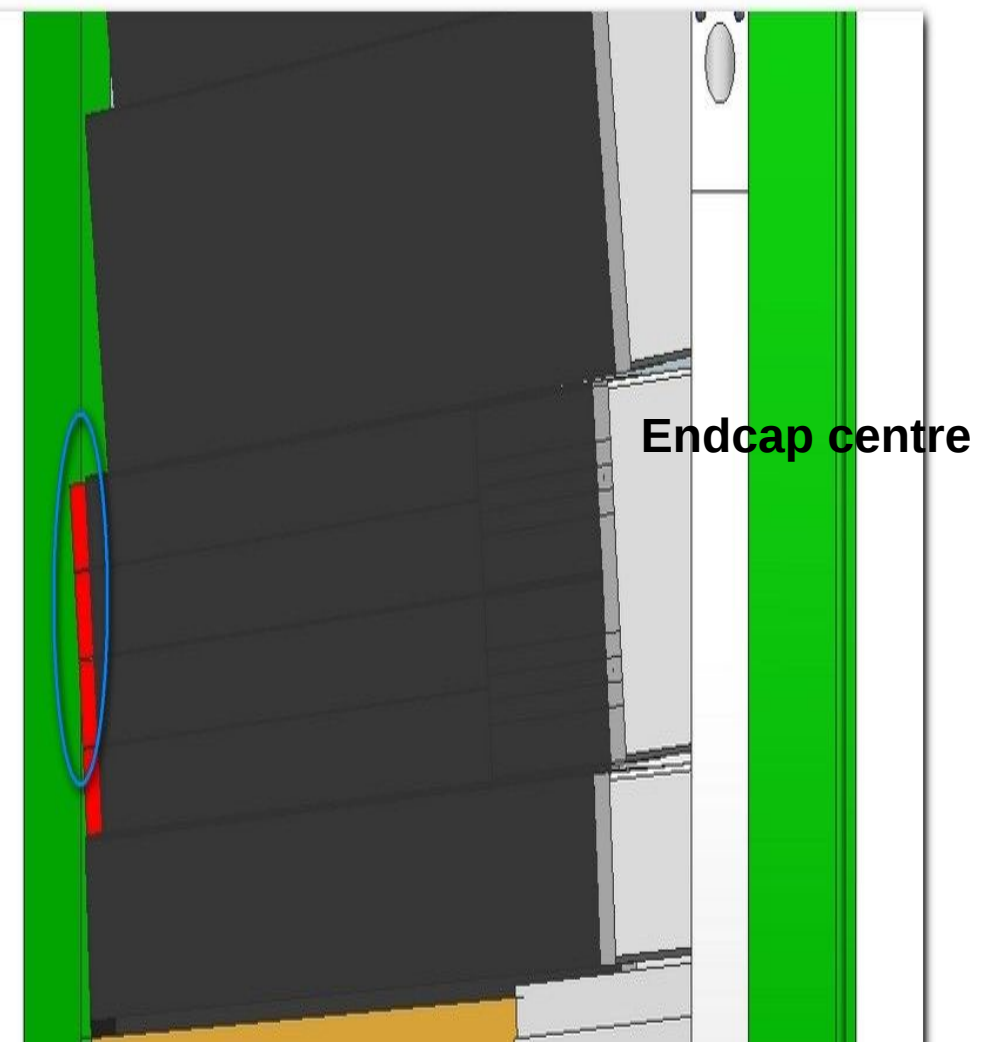
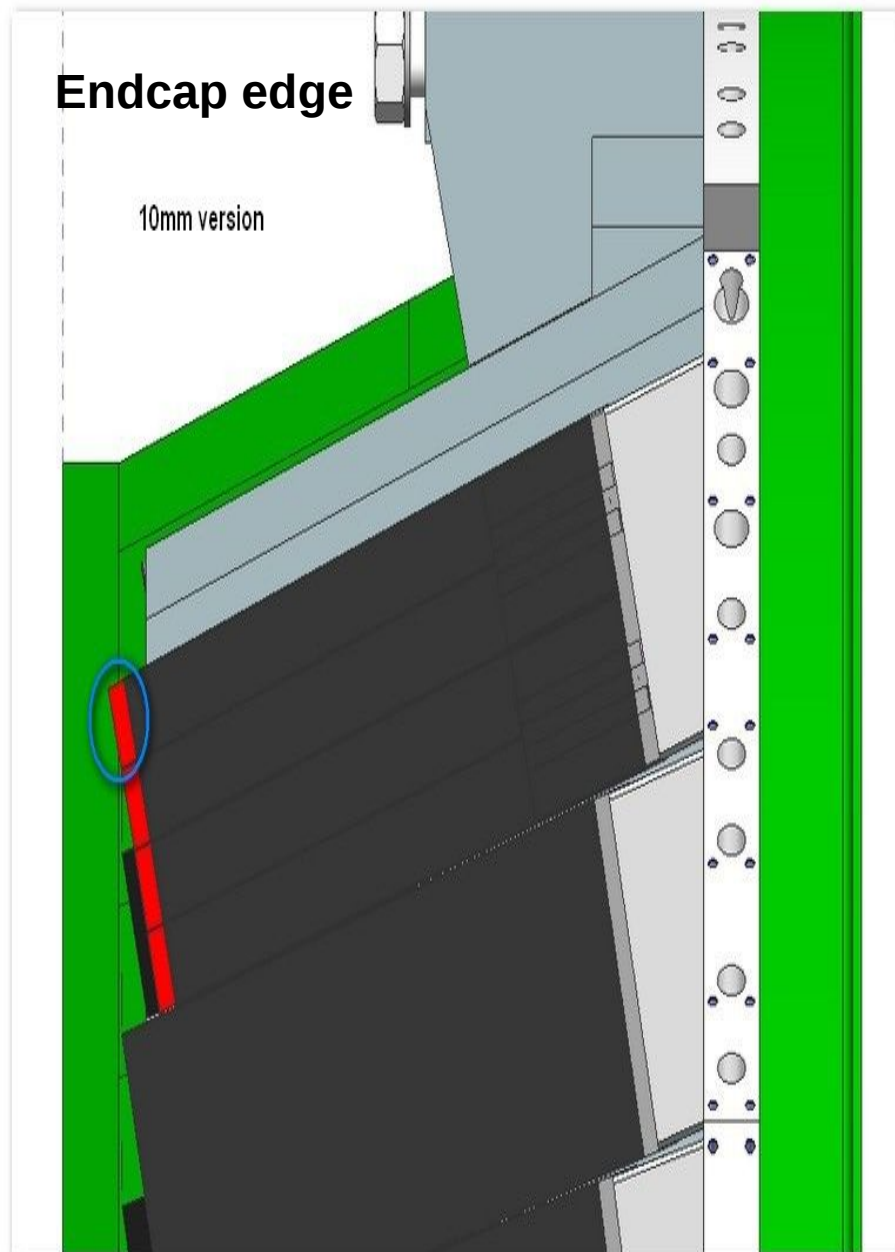


# **PANDA FW Endcap EMC: Mechanical constraints For the TOF detector**

*Henk Smit, Riemer Bergsma,  
Michel Lindemulder (mech.  
engineering),  
Annelie Kluttig (research engineer),  
Herbert Löhner  
Myroslav Kavatsyuk  
KVI Groningen*

# Extra detector in front of PWO crystal (10 mm)

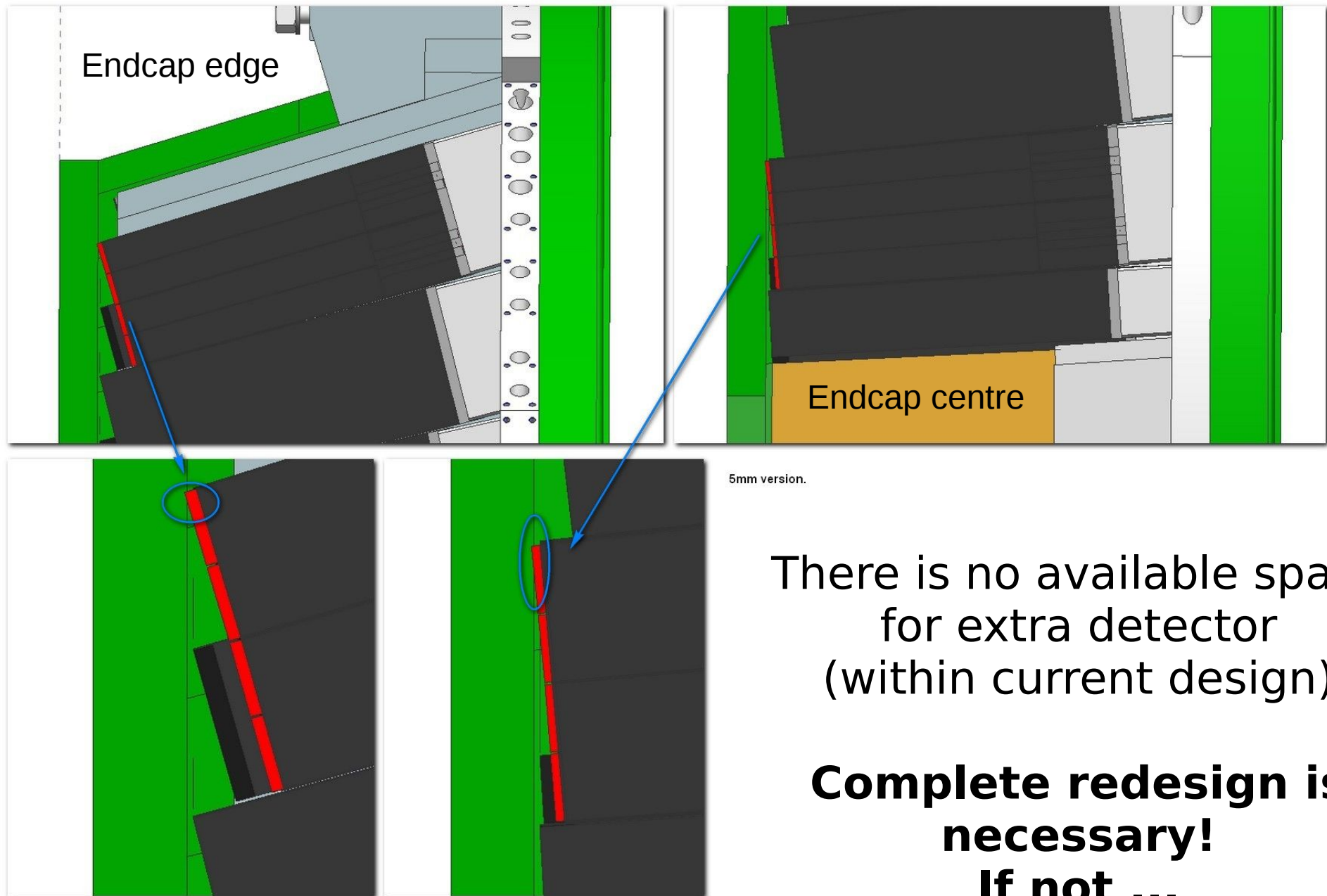


There is no available space  
for extra detector  
(within current design)



KVI

# Extra detector in front of PWO crystal (5 mm)



There is no available space  
for extra detector  
(within current design)

**Complete redesign is  
necessary!  
If not ...**

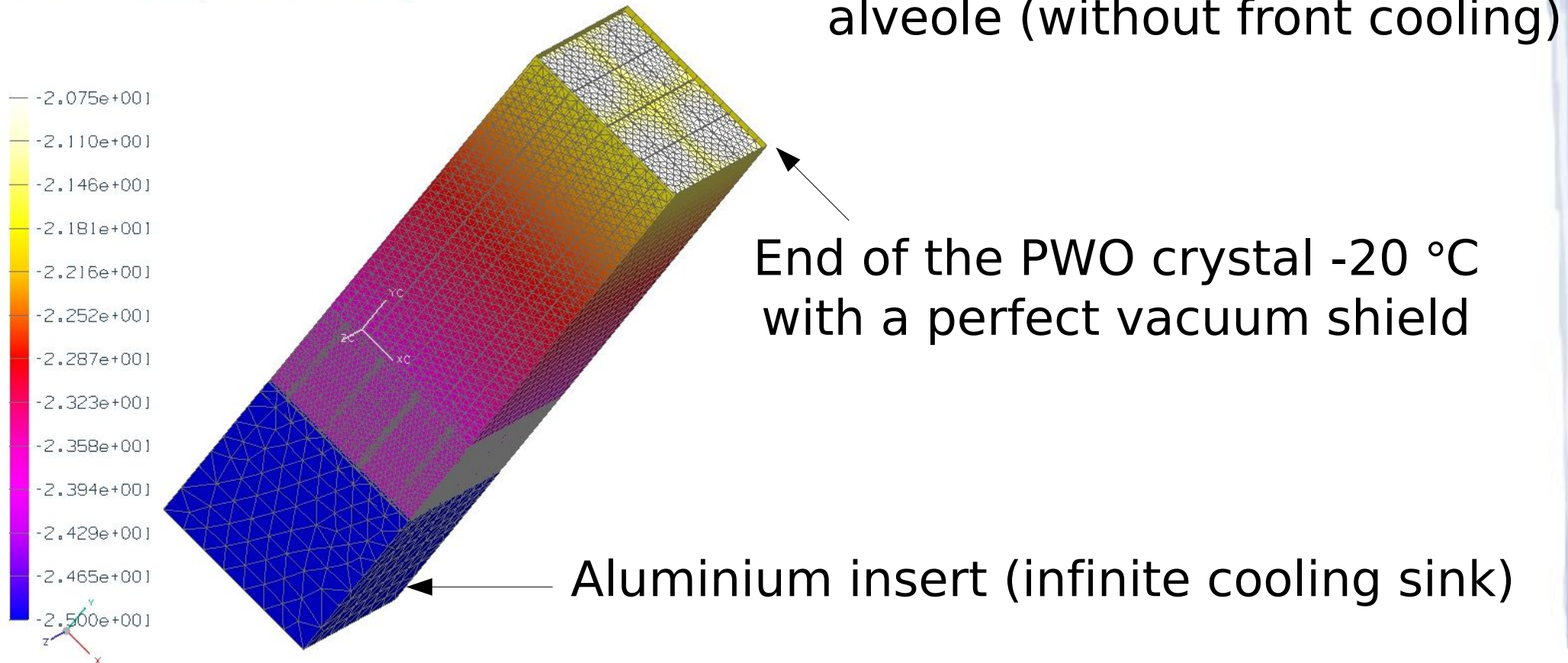
To fit new TOF detectors into the endcap we have to **reduce thickness of the thermal shield**.

## The consequences:

- Have to increase power of the cooling machine
- Temperature of the crystals will not be affected (if the first point is fulfilled)
- The temperature of the front (warm) surface may drop to +10 °C (currently +20 °C) → **danger of condensation!**

Front cooling of crystals is absolutely necessary

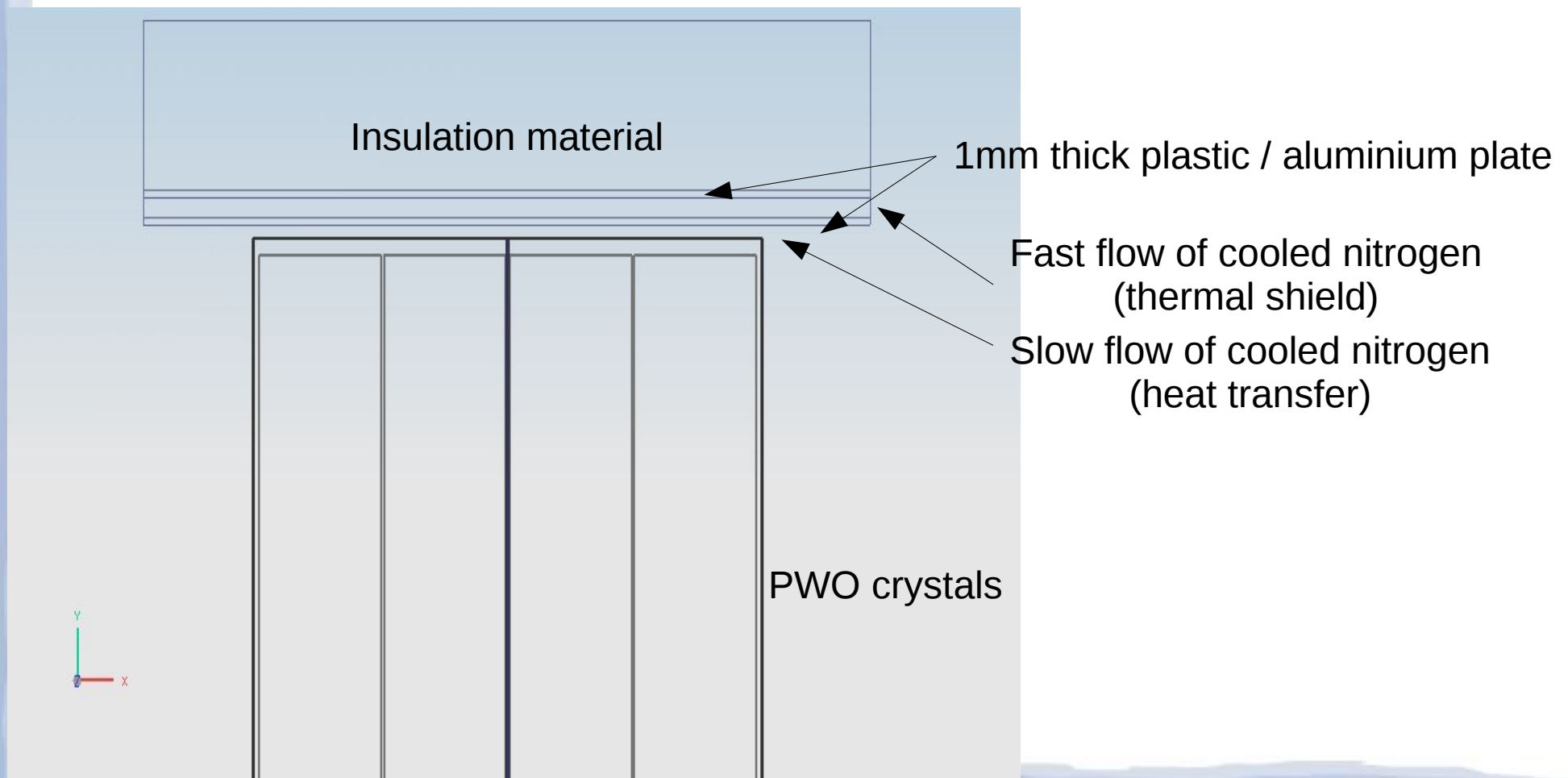
Thermal Henk plus shield\_sim1 : vacuum Result  
Load Case 1, Static Step 1  
Temperature - Nodal, Scalar  
Min : -2.500e+001, Max : 2.997e+001, C





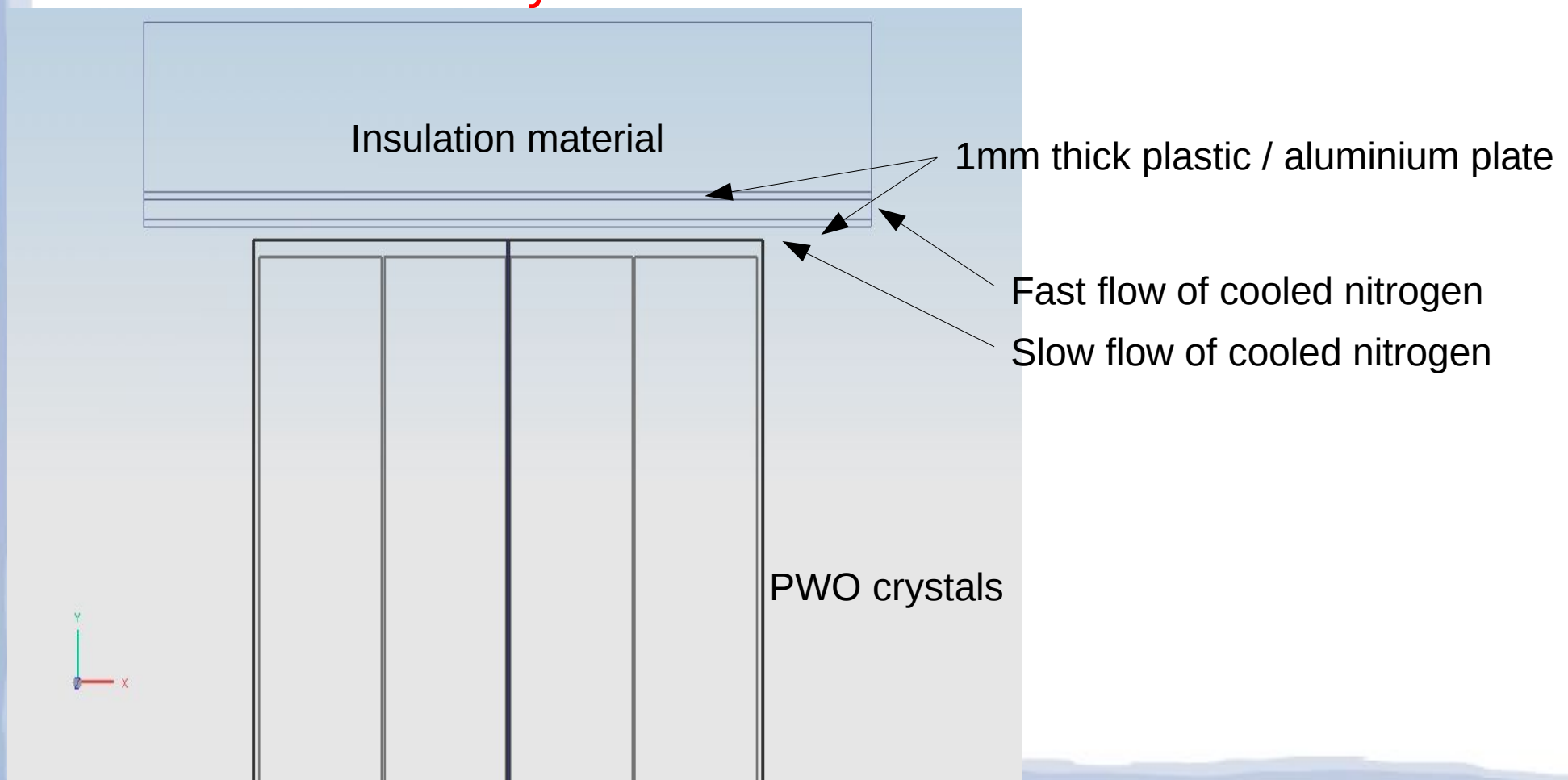
Front cooling of crystals is absolutely necessary

Current solution: Composite thermal shield



# Composite thermal shielding

- Slow flow of cooled nitrogen can remove only little amount of heat.
- Additional heat from SiPM preamplifiers **will destroy the thermal stability**



- There is no space for additional detectors in front of PWO crystals
- To include TOF detector into forward endcap complete redesign is necessary.